

W802 chip specification sheet

V1.1

Beijing Lianshengde Microelectronics Co., Ltd. (Winner Micro)

Address: 6th Floor, Yindu Building, No. 67 Fucheng Road, Haidian District, Beijing

Tel: +86-10-62161900

Website: www.winnermicro.com

Document modification record

Version	revision time	Revision history	author	review
V1.0	2023/7/17	Create document	HMX	CYC,LGH
V1.1	2023/8/2	Add silk screen information	HMX	

Table of contents

Document modification record.....	5
1 Overview	4
2 Characteristics	4
3 Chip structure	6
4Address space division.....	7
5 Function description	10
5.1 SDIO HOST controller.....	10
5.2 SDIO Device Controller.....	11
5.3 High-speed SPI device controller.....	11
5.4 DMA controller.....	11
5.5 Clock and reset.....	12
5.6 Memory Manager.....	12
5.7 Digital baseband	12
5.8 MAC Controller.....	13
5.9 Security system	13
5.10 FLASH controller.....	14
5.11 RSA encryption module.....	14
5.12 Universal hardware encryption module.....	14

5.13	I2C controller	15
5.14	Master/Slave SPI Controller.....	15
5.15	UART controller.....	15
5.16	GPIO controller.....	16
5.17	Timer	16
5.18	Watchdog Controller.....	16
5.19	RF Configurator.....	16
5.20	RF transceiver.....	16
5.21	PWM controller.....	17
5.22	I2S controller	17
5.23	7816/UART Controller	17
5.24	PSRAM interface controller.....	18
5.25	ADC.....	19
5.26	Touch Sensor Touch Button Controller.....	19
6	Pin definition	20
7	Electrical Characteristics	twenty three
7.1	Limit parameters	twenty three
7.2	RF power consumption parameters.....	twenty three
7.3	Wi-Fi radio	twenty four

7.4 Bluetooth RF	25
7.4.1 Legacy Bluetooth RF	25
7.4.2 Bluetooth Low Energy Radio	28
8 Packaging information	30
9 Silk screen information	32

1 Overview

The W802 chip is a secure IoT Wi-Fi/Bluetooth dual-mode SoC chip. The chip provides rich digital function interfaces. Support 2.4G

IEEE802.11b/g/n Wi-Fi communication protocol; supports BT/BLE dual-mode working mode and BT/BLE4.2 protocol. Chip integrated 32-bit

CPU processor, built-in UART, GPIO, SPI, I2C, I2S, 7816, SDIO, ADC, PSRAM, Touch Sensor and other digital interfaces

port; supports TEE security engine, supports multiple hardware encryption and decryption algorithms, built-in DSP, floating point operation unit and security engine, supports code security rights

Limit settings, support multiple security measures such as firmware encrypted storage, firmware signature, secure debugging, secure upgrade, etc. to ensure product security features. Applicable to

It is used in a wide range of IoT fields such as smart home appliances, smart homes, smart toys, wireless audio and video, industrial control, and medical monitoring.

2 features

• Chip appearance

• QFN56 package, 6mm x 6mm

• MCU Features

• Integrated 32-bit XT804 processor, operating frequency 240MHz, built-in DSP, floating point operation unit and security engine

• Integrated PSRAM interface, supports up to 64M bit external PSRAM memory

• Integrated high-speed QSPI interface, supports external Flash memory

• Integrated 6-channel UART high-speed interface, supporting up to 2M bps

• Integrated 4-channel 12-bit ADC, maximum sampling rate 1KHz

• Integrated 1 high-speed slave SPI interface, supporting up to 50MHz

• Integrated 1 master/slave SPI interface

• Integrated 1 SDIO_HOST interface, supports SDIO2.0, SDHC, MMC4.2

• Integrate 1 SDIO_DEVICE, support SDIO2.0, maximum operating frequency 200Mbps

• Integrated 1 I²C controller

• Integrated GPIO controller, supports up to 37 GPIOs

• Integrated 5-way PWM interface

• Integrated 1-way Duplex I²S controller

• Integrated 1 7816 interface

• Integrated 13 Touch Sensors

• Integrated 1-way Wakeup interface

• Security Features

• The MCU has a built-in Tee security engine, and the code can distinguish between the secure world and the non-secure world.

• Integrated SASC/TIPC, memory and internal modules/interfaces can be configured with security attributes to prevent non-security code access

• Enable firmware signature mechanism to achieve safe boot/upgrade

• Equipped with firmware encryption function to enhance code security

• Firmware encryption keys are distributed using asymmetric algorithms to enhance key security

• Hardware encryption module: RC4, AES128, DES/3DES, SHA1/MD5, CRC32, 2048 RSA, true random number generator

• Wi-Fi Features

• Support GB15629.11-2006, IEEE802.11 b/g/n

• Support Wi-Fi WMM/WMM-PS/WPA/WPA2/WPS

• Support EDCA channel access method

• Support 20/40M bandwidth working mode

• Supports STBC, GreenField, Short-GI, and reverse transmission

• Support AMPDU, AMSDU

• Supports IEEE802.11n MCS 0~7 and MCS32 physical layer transmission rate levels, with the transmission rate up to 150Mbps

• Supports Short Preamble when sending at 2/5.5/11Mbps rate

• Supports HT-immediate Compressed Block Ack, Normal Ack, and No Ack response methods

• Support CTS to self

• Supports Station, Soft-AP, Soft-AP/Station functions

• Bluetooth features

• Integrated Bluetooth baseband processor/protocol processor, supports BT/BLE dual-mode working mode, and supports BT/BLE4.2 protocol

• Low power consumption mode

• 3.3V single power supply

• Support Wi-Fi energy-saving mode power consumption management

• Supports work, sleep, standby, and shutdown working modes

• Standby power consumption is less than 10uA

3 chip structure

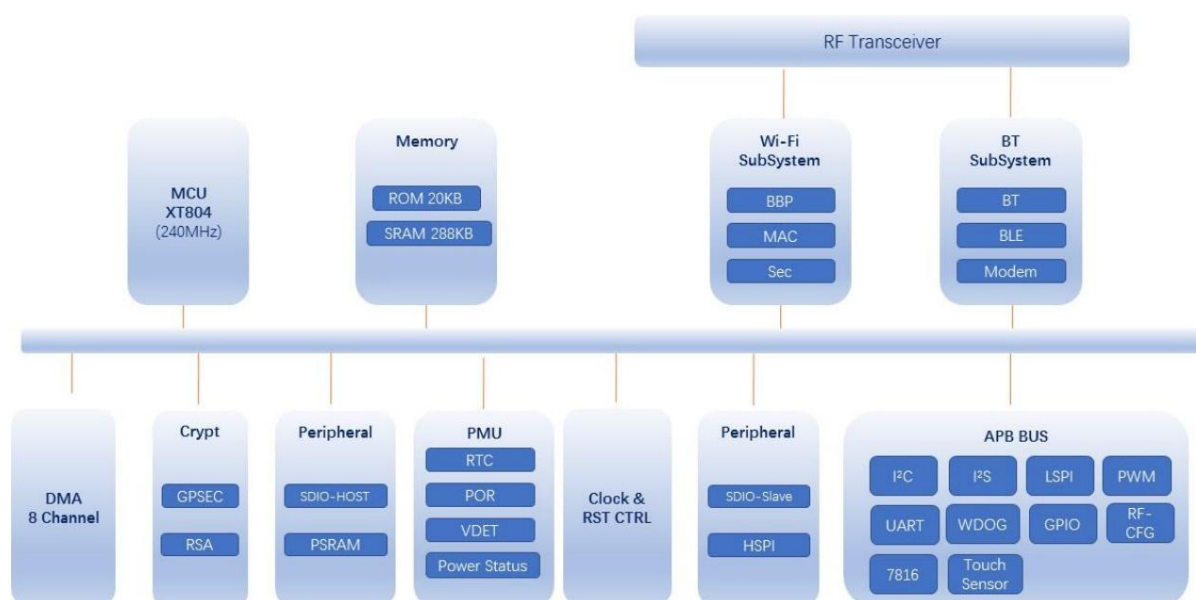


Figure 3-1 W802 chip structure diagram

4 Address space division

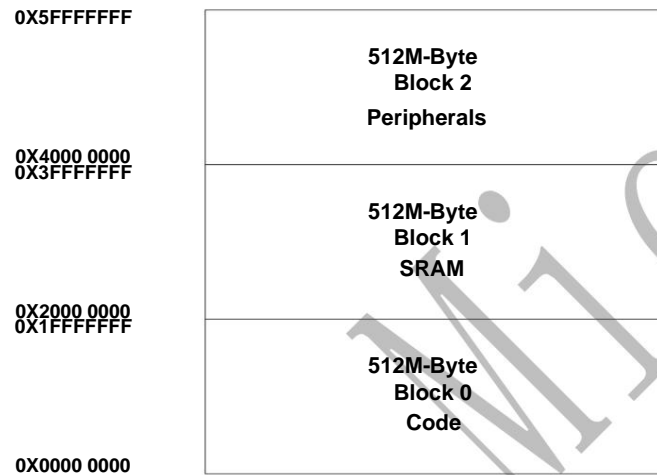


Figure 4-1 Address space mapping

Table 4-1 Detailed division of bus device address space

bus slave	BootMode=0	Address space segmentation	Remark
ROM	0x0000 0000 ~ 0x0000 4FFF		Store the solidified firmware code
FLASH	0x0800 0000 ~ 0x0FFF FFFF		As a dedicated instruction memory.
SRAM	0x2000 0000 ~ 0x2002 7FFF		Firmware Memory and Instruction Store
Mac RAM	0x2002 8000 ~ 0x2004 7FFF		SDIO/H-SPI/UART data cache

PSRAM	0x3000 0000 ~ 0x3080 0000		Peripheral memory
CONFIG	0x4000 0000 ~ 0x4000 2FFF	0x4000 0000 ~ 0x4000 05FF	RSA configuration space
		0x4000 0600 ~ 0x4000 07FF	GPSEC configuration space
		0x4000 0800 ~ 0x4000 09FF	DMA configuration space
		0x4000 0A00 ~ 0x4000 0CFF	SDIO_HOST configuration space
		0x4000 0D00 ~ 0x4000 0DFF	PMU configuration space
		0x4000 0E00 ~ 0x4000 0EFF	Clock and Reset configuration space
		0x4000 0F00 ~ 0x4000 0FFF	MacPHY Router configuration space
		0x4000 1000 ~ 0x4000 13FF	BBP configuration space
		0x4000 1400 ~ 0x4000 17FF	MAC configuration space
		0x4000 1800 ~ 0x4000 1FFF	SEC configuration space
		0x4000 2000 ~ 0x4000 21FF	FLASH Controller configuration space
		0x4000 2200 ~ 0x4000 23FF	PSRAM_CTRL configuration space
		0x4000 2400 ~ 0x4000 25FF	SDIO Slave configuration space
		0x4000 2600 ~ 0x4000 27FF	H-SPI configuration space
		0x4000 2800 ~ 0x4000 29FF	SD Wrapper configuration space
		0x4000 2A00 ~ 0x4000 A9FF	BT Core configuration space
		0x4000 B000 ~ 0x4000 B0FF	SASC-B1 Level 1 bus memory security Configuration module
		0x4000 B100 ~ 0x4000 B1FF	SASC-Flash Flash security configuration

			module
		0x4000 B200 ~ 0x4000 B2FF SASC-B2 secondary bus memory security	
			Configuration module
APB	0x4001 0000 ~ 0x4001	0x4001 0000 ~ 0x4001 01FF I2C master	
	C000	0x4001 0200 ~ 0x4001 03FF Sigma ADC	
		0x4001 0400 ~ 0x4001 05FF SPI master	
		0x4001 0600 ~ 0x4001 07FF UART0	
		0x4001 0800 ~ 0x4001 09FF UART1	
		0x4001 0A00 ~ 0x4001 0BFF UART2	
		0x4001 0C00 ~ 0x4001 0DFF UART3	
		0x4001 0E00 ~ 0x4001 0FFF UART4	
		0x4001 1000 ~ 0x4001 11FF	
		0x4001 1200 ~ 0x4001 13FF GPIO-A	
		0x4001 1400 ~ 0x4001 15FF GPIO-B	
		0x4001 1600 ~ 0x4001 17FF WatchDog	
		0x4001 1800 ~ 0x4001 19FF Timer	
		0x4001 1A00 ~ 0x4001 1BFF RF_Controller	
		0x4001 1C00 ~ 0x4001 1DFF	
		0x4001 1E00 ~ 0x4001 1FFF PWM	
		0x4001 2000 ~ 0x4001 21FF I2S	
		0x4001 2200 ~ 0x4001 23FF BT-modem	
		0x4001 2400 ~ 0x4001 25FF	

		0x4001 2600 ~ 0x4001 27FF TIPC	Interface security settings
		0x4001 4000 ~ 0x4001 BFFF RF_BIST DAC transmit memory	
		0x4001 C000 ~ 0x4003 BFFF RF_BIST ADC receiving memory	
		0x4003 C000 ~ 0x5FFF FFFF RSV	

5 Function description

5.1 SDIO HOST controller

The SDIO HOST device controller provides a digital interface to access Secure Digital Input and Output Cards (SDIO) and MMC cards. were able

Access SDIO devices and SD card devices that are compatible with the SDIO 2.0 protocol. The main interfaces are CK, CMD and 4 data lines.

- Compatible with SD card specification 1.0/1.1/2.0 (SDHC)
- Compatible with SDIO memory card specification 1.1.0
- Compatible with MMC specification 2.0~4.2
- Configurable interface clock rate, supports host rate 0~50MHz
- Support standard MMC interface
- Supports Blocks up to 1024 bytes
- Support soft reset function
- Automatic Command/Response CRC generation/verification
- Automatic data CRC generation/verification
- Configurable timeout detection
- Supports SPI, 1-bit SD and 4-bit SD modes
- Support DMA data transfer

5.2 SDIO Device Controller

SDIO2.0 device-side interface completes the interaction with host data. Internally integrated 1024Byte asynchronous FIFO to complete the data between the host and the chip

Interaction.

- Compatible with SDIO card specification 2.0
- Support host speed 0~50MHz
- Supports Blocks up to 1024 bytes
- Support soft reset function
- Supports SPI, 1-bit SD and 4-bit SD modes

5.3 High-speed SPI device controller

Compatible with the general SPI physical layer protocol, by agreeing on the data format for interaction with the host, the host can access the device at high speed, and the maximum supported operating frequency is

50Mbps.

- Compatible with universal SPI protocol
- Selectable level interrupt signal
- Supports up to 50Mbps rate
- Simple frame format, full hardware parsing and DMA

5.4 DMA controller

Supports up to 8 channels, 16 DMA request sources, and supports linked list structure and register control.

- Amba2.0 standard bus interface, 8 DMA channels
- Support DMA operation based on memory linked list structure
- Software configures 16 hardware request sources
- Support 1, 4-burst operation mode

- Supports byte, half-word, word operations

- The source and destination addresses remain unchanged or can be configured in sequential increments or operate cyclically within a predefined address range.

- Synchronize DMA request and DMA response hardware interface timing

5.5 Clock and reset

Supports the control of chip clock and reset system. Clock control includes clock frequency conversion, clock shutdown and adaptive gate control; reset control includes system and

And soft reset control of sub-modules.

5.6 Memory Manager

Supports the configuration of the sending and receiving buffer size, as well as control information such as the base address of the MAC access buffer, the number of buffers, and the upper limit of frame aggregation.

5.7 Digital baseband

Supports IEEE802.11a/b/g/e/n (1T1R) transmitter and receiver algorithm implementation, main parameters:

- Data rate: 1~54Mbps (802.11a/b/g), 6.5~150Mbps (802.11n)

- MCS format: MCS0~MCS7, MCS32 (40MHz HT Duplicate mode)

- Support 40MHz bandwidth non-HT Duplicate mode, 6M/54M

- Signal bandwidth: 20MHz, 40MHz

- Modulation method: DSSS (DBPSK, DQPSK, CCK) and OFDM (BPSK, QPSK, 16QAM, 64QAM)

- Implement 1T1R MIMO-OFDM spatial multiplexing

- Support Short GI mode

- Supports legacy mode and Mixed mode

- Supports transmission and reception of 20M upper and lower sideband signals under 40MHz bandwidth

- Supports STBC reception of MCS0~7, 32

- Support Green Field mode

5.8 MAC Controller

Supports IEEE802.11a/b/g/e/n MAC sublayer protocol control. Specific specifications include:

- Support EDCA channel access method
- Support CSMA/CA, NAV and TXOP protection mechanisms
- Beacon, Mng, VO, VI, BE, BK five-way sending queue and QoS
- Support single and broadcast multicast frame reception and transmission
- Support RTS/CTS, CTS2SELF, Normal ACK, No ACK frame sequence
- Supports retransmission mechanism as well as retransmission rate and power control
- Supports MPDU hardware aggregation and deaggregation and Immediate BlockAck mode
- Support RIFS, SIFS, AIFS
- Support reverse transmission mechanism
- Supports TSF timing and is software configurable
- Support MIB statistics

5.9 Security system

Supports the security algorithm specified by the IEEE802.11a/b/g/e/n protocol, and cooperates to complete the encryption and decryption of sent and received data frames.

- Meet the encryption and decryption throughput rate greater than 150Mbps
- Amba2.0 standard bus interface
- Support WAPI security mode 2.0
- Supports WEP security mode-64-bit encryption
- Supports WEP security mode-128-bit encryption
- Support TKIP security mode
- Support CCMP security mode

5.10 FLASH controller

- Provide bus access to FLASH interface
- Support SPI, Quad SPI interface for external Flash
- External Flash supports up to 16MB
- Support hardware encryption module to encrypt Flash
- Provide system bus and data bus access arbitration
- Implement CACHE cache system to improve FLASH interface access speed
- Provide compatibility with different QFlash

5.11 RSA encryption module

RSA computing hardware coprocessor provides Montgomery (FIOS algorithm) modular multiplication computing function. Cooperate with the RSA software library to implement the RSA algorithm.

Supports 128-bit to 2048-bit modular multiplication.

5.12 Universal hardware encryption module

The encryption module automatically completes the encryption of the source address space data of the specified length, and automatically writes the encrypted data back to the specified destination address space after completion;

Support SHA1/MD5/RC4/DES/3DES/AES/CRC/TRNG.

- Support SHA1/MD5/RC4/DES/3DES/AES/CRC/TRNG encryption algorithm
- DES/3DES supports ECB and CBC modes
- AES supports three modes: ECB, CBC and CTR
- CRC supports four modes: CRC8, CRC16_MODBUS, CRC16_CCITT and CRC32
- CRC supports input/output reverse
- SHA1/MD5/CRC supports continuous multi-packet encryption
- Built-in true random number generator, also supports seed to generate pseudo-random numbers

5.13 I2C controller

APB bus protocol standard interface, only supports main device controller, I²C working frequency supports configurable, 100K-400K.

5.14 Master/Slave SPI Controller

Supports synchronous SPI master-slave functionality. Its working clock is the system internal bus clock. Its characteristics are as follows:

- The transmit and receive paths each have 8 word depth FIFOs
- master supports 4 formats of Motorola SPI (CPOL, CPHA), TI timing, macrowire timing
- slave supports 4 formats of Motorola SPI (CPOL, CPHA);
- Support full duplex and half duplex
- The main device supports bit transmission, with a maximum support of 65535bit transmission.
- The slave device supports transmission modes of various lengths of bytes
- The maximum clock frequency of SPI_Clk input from the slave device is 1/6 of the system clock

5.15 UART controller

- The device side complies with the APB bus interface protocol
- Support interrupt or polling working mode
- Supports DMA transfer mode, with 32-byte FIFO for sending and receiving.
- Programmable baud rate
- 5-8bit data length, and parity polarity configurable
- 1 or 2 stop bits configurable
- Support RTS/CTS flow control
- Support Break frame sending and receiving
- Overrun, parity error, frame error, rx break frame interrupt indication

• Maximum 16-burst byte DMA operation

5.16 GPIO controller

Configurable GPIO, software-controlled input and output, hardware-controlled input and output, configurable interrupt mode.

The starting addresses of the GPIOA and GPIOB registers are different, but their functions are the same.

5.17 Timer

Microsecond and millisecond timing (the number of counts is configured according to the clock frequency), and six configurable 32-bit counters are implemented. When the count configured by the corresponding calculator is completed,

When completed, a corresponding interrupt is generated.

5.18 Watchdog Controller

Supports "watchdog" function. Observe correct software behavior and allow global reset after system crash. "Watchdog" generates a periodic

Interrupt, the system software must respond to this interrupt and clear the interrupt flag; if the interrupt flag is not cleared for a long time due to system crash, then

Generates a hard reset to globally reset the system.

5.19 RF Configurator

Implemented synchronous SPI master functionality. Its working clock is the system internal bus clock. Its characteristics are as follows:

• The transmit and receive paths each have 1 word depth FIFO

5.20 RF transceiver

• The RF transceiver part includes modules including power amplifier, transmit channel, receive channel, phase locked loop and SPI. By adjusting the control

Control ports SHDN, RXEN and TXEN to change the chip working status

• The receiving path adopts a zero-IF structure to directly convert the radio frequency signal into two baseband I and Q outputs. The RF front-end works at 2.4GHz,

Contains low-noise amplifier and quadrature mixer; baseband consists of low-pass filter and variable gain amplifier to achieve channel filtering and gain control;

The driver amplifier provides different DC outputs for the ADC interface

• The transmit path includes: programmable control filter, upconversion mixer, variable gain amplifier and power amplifier. The transmit path also uses direct

Frequency conversion structure. The output signal of the DAC passes through a low-pass filter to filter out the image frequency and out-of-band noise. The PA output is a differential output driver

Off-chip antenna

5.21 PWM controller

• 5-channel PWM signal generation function

• 2-channel input signal capture function (PWM0 and PWM4 two channels)

• Output signal frequency range 3Hz~160KHz

• Maximum accuracy of duty cycle: 1/256

• Counter width inserted into dead zone: 8bit

5.22 I²S controller

• Support AMBA APB bus interface, 32bit single read and write operations

• Supports master and slave modes and can work in duplex

• Supports 8/16/24/32 bit width, the maximum sampling frequency is 128KHz

• Supports mono and stereo modes

• Compatible with I²S and MSB justified data formats, compatible with PCM A/B format

• Supports DMA request read and write operations. Only supports word-by-word operations

5.23 7816/UART controller

• Compatible with UART and 7816 interface functions

• The device side complies with the APB bus interface protocol

• Support interrupt or polling working mode

• Supports DMA transfer mode, with 32-byte FIFO for sending and receiving.

• DMA can only operate on a byte basis, with a maximum of 16-burst byte DMA operations

Serial port function:

- Programmable baud rate
- 5-8bit data length, and parity polarity configurable
- 1 or 2 stop bits configurable
- Support RTS/CTS flow control
- Support Break frame sending and receiving
- Overrun, parity error, frame error, rx break frame interrupt indication

7816 interface functions:

- Compatible with ISO-7816-3 T=0, T=1 mode
- Compatible with EVM2000 protocol
- Configurable guard time (11 ETU-267 ETU)
- Forward/reverse convention can be configured by software
- Support send/receive parity check and retransmission function
- Supports 0.5 and 1.5 stop bit configurations

5.24 PSRAM interface controller

The PSRAM controller with built-in SPI/QSPI interface supports external PSRAM device access and provides bus-based PSRAM read, write and erase operations.

The maximum read and write speed is 80MHz.

- Supports read and write access to external PSRAM
- Configurable for SPI and QSPI
- SPI/QSPI clock frequency configurable
- Support BURST INC mode access
- Supports semi-sleep mode of PSRAM

5.25 ADC

The acquisition module based on Sigma-Delta ADC completes the acquisition of up to 4 analog signals. The sampling rate is controlled by the external input clock.

It collects input voltage and can also collect chip temperature, supporting input calibration and temperature compensation calibration.

5.26 Touch Sensor touch button controller

The basic functions of the module are as follows:

• Supports up to 13 channels of Touch Sensor scanning

• Record the scanning results of each Touch Sensor

• Report scan results through interruption

6 pin definition

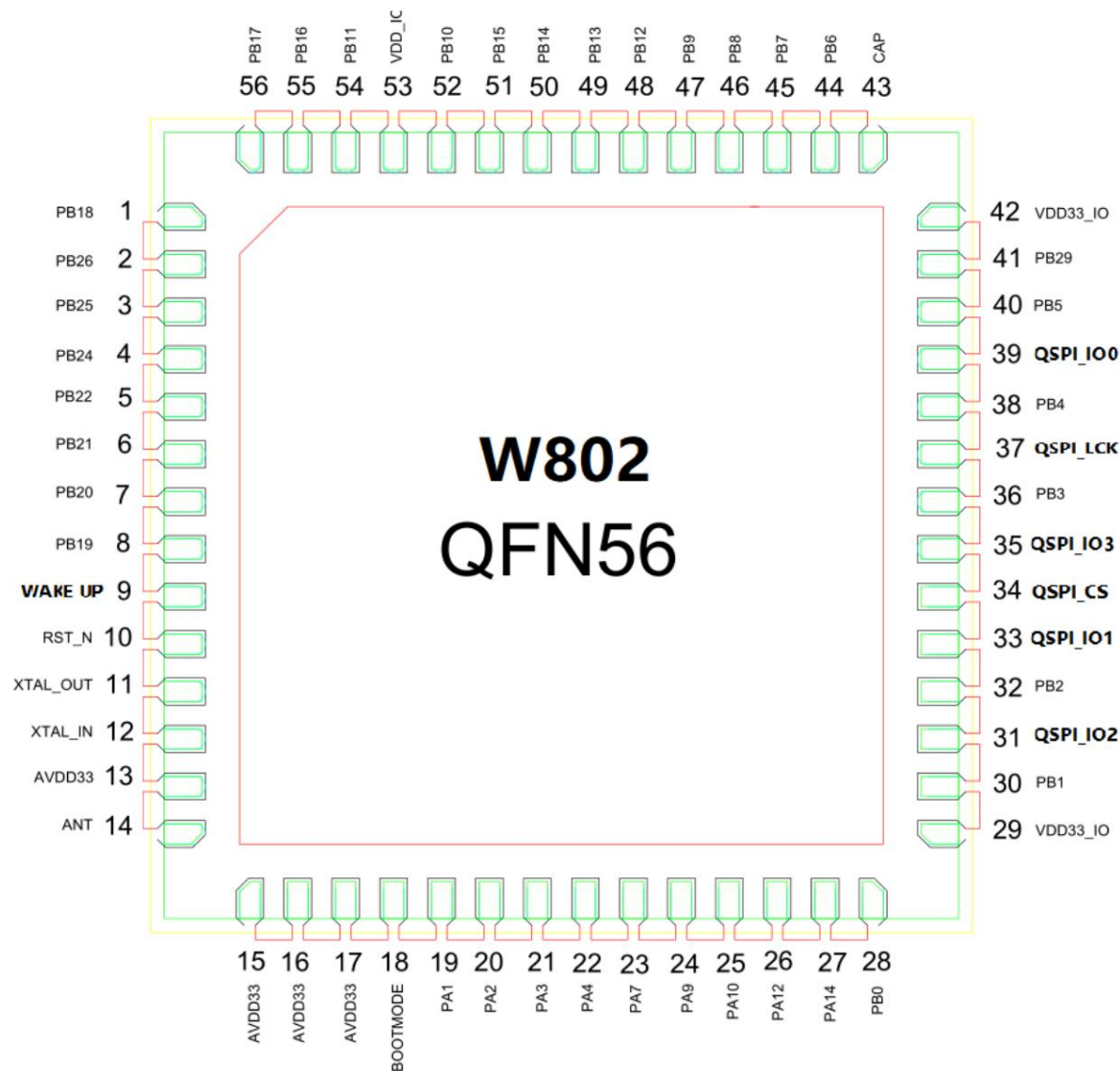


Figure 6-1 W802 pin layout diagram (QFN56)

Table 6-1W802 pin assignment definition (QFN56)

No.	Name	Type	Pin	function after reset	Reuse function	Maximum frequency	pull-down capability	driving capability
1	PB_18	I/O	GPIO, input, high impedance	UART5_TX	20MHz	UP/DOWN	12mA	
2	PB_26	I/O	GPIO, input, high impedance	LSPI_MOSI/PWM4	20MHz	UP/DOWN	12mA	
3	PB_25	I/O	GPIO, input, high impedance	LSPI_MISO/PWM3	20MHz	UP/DOWN	12mA	

4	PB_24	I/O GPIO, input, high impedance	LSPI_CK/PWM2	20MHz	UP/DOWN	12mA
5	PB_22	I/O GPIO, input, high impedance	UART0_CTS/PCM_CK	2MHz	UP/DOWN	12mA
6	PB_21	I/O GPIO, input, high impedance	UART0_RTS/PCM_SYNC	2MHz	UP/DOWN	12mA
7	PB_20	I/O UART_RX	UART0_RX/PWM1/UART1_CTS/I2C_SCL	2MHz	UP/DOWN	12mA
8	PB_19	I/O UART_TX	UART0_TX/PWM0/UART1_RTS/I2C_SDA	2MHz	UP/DOWN	12mA
9	WAKEUP	I external wake-up				
10	RESET	I RESET reset			UP	
11	XTAL_OUT	O External crystal oscillator output				
12	XTAL_IN	I External crystal oscillator input				
13	AVDD33	P chip power supply, 3.3V				
4	ANT	I/O RF antenna				
15	AVDD33	P chip power supply, 3.3V				
16	AVDD33	P chip power supply, 3.3V				
17	AVDD33_AUX	P chip power supply, 3.3V				
18	BOOTMODE I/O	BOOTMODE	I2S_MCLK/LSPI_CS/PWM2/I2S_DO	30MHz	UP/DOWN	12mA
19	PA_1	I/O JTAG_CK	JTAG_CK/I2C_SCL/PWM3/I2S_LRCK/ADC_0	20MHz	UP/DOWN	12mA
20	PA_2	I/O GPIO, input, high impedance	UART1_RTS/UART2_TX/PWM0/UART3_RTS/ADC_3	20MHz	UP/DOWN	12mA
	PA_3	I/O GPIO, input, high impedance	UART1_CTS/UART2_RX/PWM1/UART3_CTS/ADC_2	20MHz	UP/DOWN	12mA
	PA_4	I/O JTAG_SWO	JTAG_SWO/I2C_SDA/PWM4/I2S_BCK/ADC_1	20MHz	UP/DOWN	12mA
	PA_7	I/O GPIO, input, high impedance	PWM4/LSPI_MOSI/I2S_MCK/I2S_DI	25MHz	UP/DOWN	12mA
	PA_9	I/O GPIO, input, high impedance	MMC_CLK/UART4_RX/UART5_RX/I2S_LRCLK/Touch_1	50MHz	UP/DOWN	12mA
25	PA_10	I/O GPIO, input, high impedance	MMC_CMD/UART4_RTX/PWM0/I2S_DO/Touch_2	50MHz	UP/DOWN	12mA
26	PA_12	I/O GPIO, input, high impedance	MMC_DAT1/UART5_TX/PWM2/Touch_Cap (CMOD)	50MHz	UP/DOWN	12mA
27	PA_14	I/O GPIO, input, high impedance	MMC_DAT3/UART5_CTS/PWM4/Touch_Cap(CDC)	50MHz	UP/DOWN	12mA
28	PB_0	I/O GPIO, input, high impedance	PWM0/LSPI_MISO/UART3_TX/PSRAM_CK/Touch_3	80MHz	UP/DOWN	12mA
29	VDD33IO	P IO power supply, 3.3V				
30	PB_1	I/O GPIO, input, high impedance	PWM1/LSPI_CK/UART3_RX/PSRAM_CS/Touch_4	80MHz	UP/DOWN	12mA
31	QSPI_IO2 I/O		QSPI_D2	100MHz	UP/DOWN	12mA

32	PB_2	I/O GPIO	O, input, high impedance	PWM2/LSPI_CLK/UART2_TX/PSRAM_D0 /Touch_5	80MHz	UP	
33	QSPI_IO1	I/O QSPI	D1	QSPI_D1	100MHz	UP/DOWN	12mA
34	QSPI_CS	OQSPI	CS	QSPI_CS	100MHz	UP	
35	QSPI_IO3	I/O QSPI	D3	QSPI_D3	100MHz	UP	
36	PB_3	I/O GPIO	O, input, high impedance	PWM3/LSPI_MISO/UART2_RX/PSRAM_D1 /Touch_6	80MHz	UP	
37	QSPI_CLK	O QSPI	CLK	QSPI_CLK	100MHz	UP/DOWN	12mA
38	PB_4	I/O GPIO	O, input, high impedance	LSPI_CS/UART2_RTS/UART4_TX/PSRAM _D2 /Touch_7	80MHz	UP	
39	QSPI_IO0		QSPI_D0	QSPI_D0	100MHz	UP/DOWN	12mA
40	PB_5	I/O GPIO	O, input, high impedance	LSPI_MOSI/UART2_CTS/UART4_RX/PSA RM_D3 /Touch_8	80MHz	UP	
41	PB_29	I/O GPIO	O, input, high impedance	PSRAM_D1/UART0_RTS/Touch_15	80MHz	UP/DOWN	12mA
42	VDD33IO	P IO	power supply, 3.3V				
43	CAP	I	external capacitor, 4.7μF				
44	PB_6	I/O GPIO	O, input, high impedance	UART1_TX/MMC_CLK/HSPI_CLK/SDIO_CLK /Touch_9	50MHz	UP/DOWN	12mA
45	PB_7	I/O GPIO	O, input, high impedance	UART1_RX/MMC_CMD/HSPI_INT/SDIO_C MD /Touch_10	50MHz	UP/DOWN	12mA
46	PB_8	I/O GPIO	O, input, high impedance	I2S_BCK/MMC_D0/PWM_BREAK/SDIO_D0 /Touch_11	50MHz	UP/DOWN	12mA
47	PB_9	I/O GPIO	O, input, high impedance	I2S_LRCK/MMC_D1/HSPI_CS/SDIO_D1 /Touch_12	50MHz	UP/DOWN	12mA
48	PB_12	I/O GPIO	O, input, high impedance	HSPI_CLK/PWM0/UART5_CTS/I2S_BCLK	50MHz	UP/DOWN	12mA
49	PB_13	I/O GPIO	O, input, high impedance	HSPI_INT/PWM1/UART5_RTS/I2S_LRCL K	50MHz	UP/DOWN	12mA
50	PB_14	I/O GPIO	O, input, high impedance	HSPI_CS/PWM2/LSPI_CS/I2S_DO	50MHz	UP/DOWN	12mA
51	PB_15	I/O GPIO	O, input, high impedance	HSPI_DI/PWM3/LSPI_CLK/I2S_DI	50MHz	UP/DOWN	12mA
52	PB_10	I/O GPIO	O, input, high impedance	I2S_DI/MMC_D2/HSPI_DI/SDIO_D2	50MHz	UP/DOWN	12mA
53	VDD33IO	P IO	power supply, 3.3V				
54	PB_11	I/O GPIO	O, input, high impedance	I2S_DO/MMC_D3/HSPI_DO/SDIO_D3	50MHz	UP/DOWN	12mA
55	PB_16	I/O GPIO	O, input, high impedance	HSPI_DO/PWM4/LSPI_MISO/UART1_RX	50MHz	UP/DOWN	12mA
56	PB_17	I/O GPIO	O, input, high impedance	UART5_RX/PWM_BREAK/LSPI_MOSI/I2S _MCLK	20MHz	UP/DOWN	12mA

Note: 1. I = input, O = output, P = power

7 Electrical Characteristics

7.1 Limit parameters

Table 7-1 Limit parameters

parameter	name	minimum value	Typical value	maximum value	unit
Supply voltage	VDD	3.0	3.3	3.6	V
Input logic level is low	VIL	-0.3		0.8	V
Input logic level is high	VIH	2.0		VDD+0.3	V
Input pin capacitance	Cpad			2	pF
Output logic level is low	VOL			0.4	V
Output logic level is high	VOH	2.4			V
Output maximum drive capability	IMAX			twenty four	mA
Storage temperature range	TSTR	-40℃		+125℃	℃
range of working temperature	TOPR	-40℃		+85℃	℃

7.2 RF power consumption parameters

Test conditions: 3.3V power supply, emission test at 50% duty cycle.

Table 7-2 RF power consumption parameters

model	Typical value	unit
Transmit IEEE802.11b 1Mbps POUT = +19.4dBm	240	mA
Transmit IEEE802.11b 11Mbps POUT = +19.3dBm	240	mA
Transmit IEEE802.11g 54Mbps POUT = +14.7 dBm	180	mA
Send IEEE802.11n MCS7 POUT = +12dBm	175	mA
Receive IEEE802.11b/g/n	95	mA

7.3 Wi-Fi radio frequency

Table 7-3 Wi-Fi radio frequency parameters

parameter	Typical value	unit
input frequency	2.4~2.4835	GHz
Transmit power		
IEEE802.11b 11Mbps	19±2	dBm
IEEE802.11g 54Mbps	16±2	dBm
IEEE802.11nMCS7HT20	13±2	dBm
Receive sensitivity		

IEEE802.11b 1Mbps	-96	dBm
IEEE802.11b 11Mbps	-86	dBm
IEEE802.11g 54Mbps	-73	dBm
IEEE802.11g MCS7 HT20	-71	dBm
adjacent channel suppression		
IEEE802.11b 6Mbps	32	dB
IEEE802.11g 54Mbps	16	dB
IEEE802.11n HT20, MCS0	31	dB
IEEE802.11n HT20, MCS7	12	dB

7.4 Bluetooth RF

7.4.1 Traditional Bluetooth RF

Receiver-Base Rate (BR)

parameter	condition	Minimum value	Typical value	Maximum value	Unit
Sensitivity @0.1% BER			-91		dBm
Maximum received signal @0.1% BER			0		dBm
Common channel suppression ratio C/I			9		dB
out-of-band blocking	30 MHz ~ 2000 MHz		-10		dBm
	2000 MHz ~ 2400		-27		dBm
	MHz				

	2500 MHz ~ 3000		-27		dBm
	MHz				
	3000 MHz ~ 12.5 GHz		-10		dBm
Intermodulation			-39		dB

Transmitter - Base Rate (BR)

parameter	condition	Minimum value	Typical value	Maximum value	Unit
RF transmit power			6		dBm
Gain control step size			3		db
RF power control range		-10		12	dBm
20 dB bandwidth		0.918	0.923		
γf_{1avg}			159.8		
γf_{2max}			142.8		
$\gamma f_{2avg}/\gamma f_{1avg}$			0.89		
ICFT			0		
drift rate		-2.25	-2.08	2.23	kHz
Offset(DH1)		-4		-1	kHz
Offset(DH5)			0	twenty one	kHz

Receiver - Enhanced Rate (EDR)

parameter	condition	Minimum value	Typical value	Maximum value	Unit
-----------	-----------	---------------	---------------	---------------	------

π/4 DQPSK					
Sensitivity@0.01% BER			-88		dBm
Maximum received signal@0.01% BER			0		dBm
8DPSK					
Sensitivity@0.01% BER			-81		dBm
Maximum received signal@0.01% BER			0		dBm

Transmitter - Enhanced Data Rate (EDR)

parameter	condition	Minimum value	Typical value	Maximum value	Unit
RF transmit power			0		dBm
Gain control step size			3		db
RF power control range		-10		8	dBm
π/4 DQPSK max w0		-3.2		2.6	KHz
π/4DQPSKmaxwi		-5.3		-2.4	KHz
π/4 DQPSK max wi + w0		-4.8		-3.9	KHz
8DPSK max w0		-1.4		1.5	KHz
8DPSKmaxwi		-4.1		-2.9	KHz
8DPSK max wi + w0		-4.8		-4.1	KHz

π/4 DQPSK modulation accuracy	RMS DEVM		6.7		%
	99%DEVM		100		%
	Peak DEVM		14.1		%
8 DPSK modulation accuracy	RMS DEVM		6.8		%
	99%DEVM		99.99		%
	Peak DEVM		15.3		%
EDR differential phase encoding			100		%

7.4.2 Bluetooth Low Energy RF

receiver

parameter	condition	Minimum value	Typical value	Maximum value	Unit
Sensitivity@30.8% PER			-94		dBm
Maximum received signal@30.8% PER				0	dBm
out-of-band blocking	30MHz~2000MHz		-30		dBm
	2003MHz~2399MHz		-35		dBm
	2484MHz~3000MHz		-35		dBm
	3000MHz~12.5GHz		-30		dBm

Intermodulation			-47		dBm
-----------------	--	--	-----	--	-----

launcher

parameter	condition	Minimum value	Typical value	Maximum value	Unit
RF transmit power			6		dBm
Gain control step size			2		db
RF power control range		-10		12	dBm
Ƴf1avg		240.8	241.2 242		kHz
Ƴf2max		175.7	182.7 183.9		kHz
drift rate			1.5		kHz
offset			-4.3		kHz

8 Packaging information

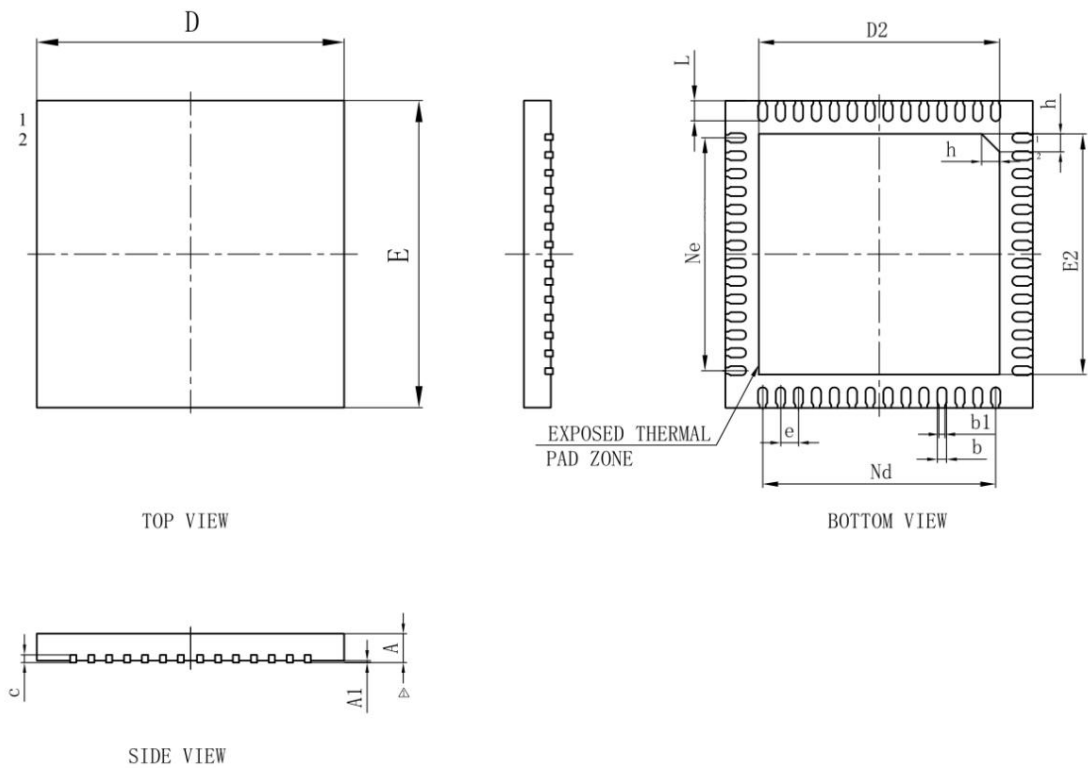


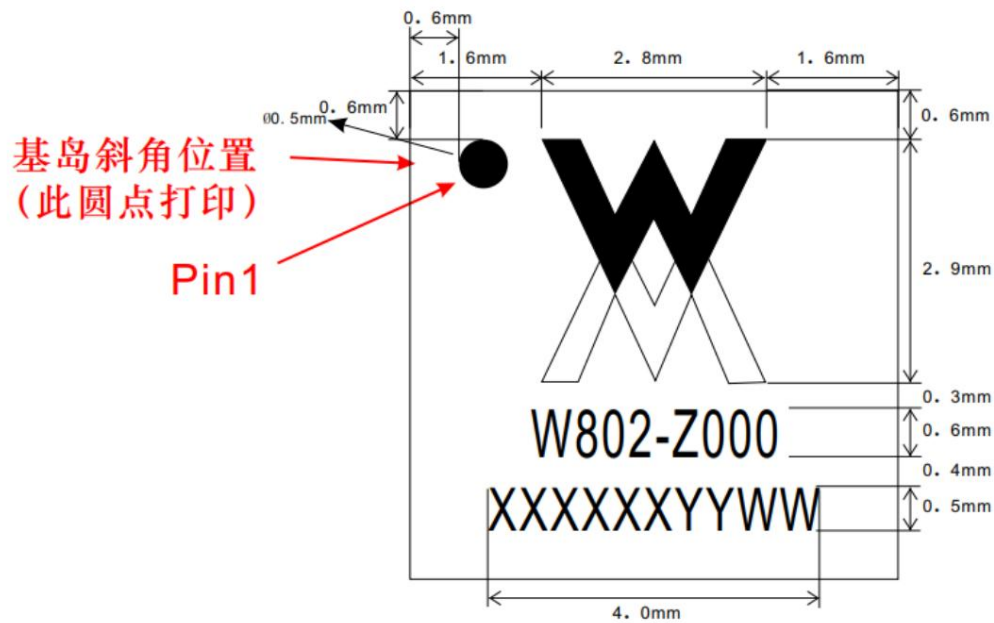
Figure 8-1 W802 packaging parameters

Table 8-1 W802 package parameter table

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
	0.80	0.85	0.90
A1	0.00	0.02	0.05
b	0.13	0.18	0.23
b1	0.12REF		
c	0.18	0.20	0.25
D	5.90	6.00	6.10

D2	4.60	4.70	4.80
e	0.35BSC		
Ne	4.55BSC		
Nd	4.55BSC		
E	5.90	6.00	6.10
E2	4.60	4.70	4.70
L	0.35	0.40	0.45
h	0.30	0.35	0.40
L/F carrier size	193x193		

9 silk screen information



Note: Font: Arial;

The third line of the seal, XXXXXX, represents the first 6 digits of the batch number of the main core, and YYWW is the year and week number (if the year and week number is given in the order, the one given shall prevail, if not given,

Print the actual offline year and week number).